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(54) Title: PHOSPHORUS-CONTAINING EPOXY RESIN

(57) Abstract: Embodiments of the present disclosure provide a phosphorus-containing epoxy resin. Embodiments of the present disclosure further include a curable composition formed with the phosphorous-containing epoxy resin and a cured epoxy formed with the phosphorus-containing epoxy resin. For the various embodiments, the cured epoxy formed with the phosphorus-containing epoxy resin can have a glass transition temperature within a range of at least 150 degrees Celsius to 200 degrees Celsius and a thermal decomposition temperature of at least 330 degrees Celsius.



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